

Patent Application

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Pepe, et al.

Serial No.: 09/938,686

Filed: October 30, 2001

For: METHOD OF MAKING  
STACKABLE LAYERS  
CONTAINING ENCAPSULATED  
INTEGRATED CIRCUIT CHIPS  
WITH ONE OR MORE  
OVERLAYING INTERCONNECT  
LAYERS

Examiner: Hung K. Vu

Group Art Unit: 2811

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**MAR 01 2004**

Irvine, California

February 19, 2004

**AMENDMENT AFTER FINAL**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Please enter the following amendment in response to the Office Action dated August 21, 2003. A request for a three-month extension of time and appropriate fees are enclosed. If necessary, please charge Deposit Account No. 01-1960.

## VI. SUMMARY

Based on the above amendments and accompanying remarks, Applicants respectfully submit that all pending claims, 2-11, 13-16, 34-36, 40-41, and 43-44, are in condition for allowance and earnestly solicits a notice thereof. Applicant encourages the Examiner to telephone the undersigned attorney if it appears that a telephone conference would facilitate allowance of the application.

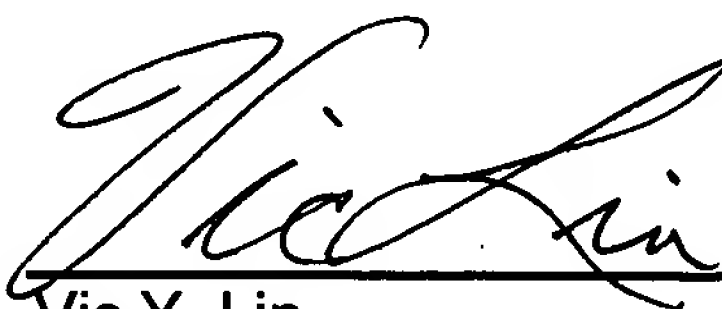
### Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on February 19, 2004  
Angela Williams



Signature  
February 19, 2004

Respectfully submitted,



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